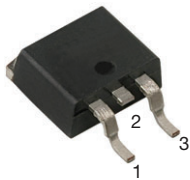
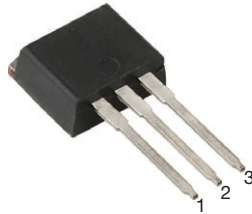
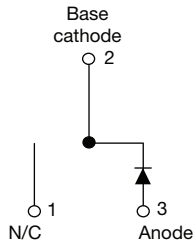
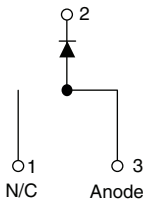


Hyperfast Rectifier, 15 A FRED Pt®


D²PAK (TO-263AB)

TO-262AA

VS-ETH1506S-M3

VS-ETH1506-1-M3

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

PRIMARY CHARACTERISTICS

| | |
|-----------------------|---|
| $I_{F(AV)}$ | 15 A |
| V_R | 600 V |
| V_F at I_F | 1.25 V |
| t_{rr} (typ.) | 21 ns |
| T_J max. | 175 °C |
| Package | D ² PAK (TO-263AB), TO-262AA |
| Circuit configuration | Single |

ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS |
|---|----------------|-----------------|-------------|-------|
| Repetitive peak reverse voltage | V_{RRM} | | 600 | V |
| Average rectified forward current | $I_{F(AV)}$ | $T_C = 139$ °C | 15 | A |
| Non-repetitive peak surge current | I_{FSM} | $T_C = 25$ °C | 160 | |
| Operating junction and storage temperatures | T_J, T_{Stg} | | -65 to +175 | °C |

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
|-------------------------------------|---------------|--|------|------|------|---------|
| Breakdown voltage, blocking voltage | V_{BR}, V_R | $I_R = 100$ μ A | 600 | - | - | V |
| | | | | | | |
| Forward voltage | V_F | $I_F = 15$ A | - | 1.8 | 2.45 | V |
| | | $I_F = 15$ A, $T_J = 150$ °C | - | 1.25 | 1.6 | |
| Reverse leakage current | I_R | $V_R = V_R$ rated | - | 0.01 | 15 | μ A |
| | | $T_J = 150$ °C, $V_R = V_R$ rated | - | 20 | 200 | |
| Junction capacitance | C_T | $V_R = 600$ V | - | 12 | - | pF |
| Series inductance | L_S | Measured lead to lead 5 mm from package body | - | 8.0 | - | nH |



| DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified) | | | | | | | |
|---|-----------|---|---|------|------|-------|----|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | t_{rr} | $I_F = 1.0\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$ | - | 21 | 26 | ns | |
| | | $I_F = 1.5\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$ | - | 25 | 36 | | |
| | | $T_J = 25\text{ }^\circ\text{C}$ | - | 29 | - | | |
| | | $T_J = 125\text{ }^\circ\text{C}$ | - | 65 | - | | |
| Peak recovery current | I_{RRM} | $T_J = 25\text{ }^\circ\text{C}$ | - | 3.9 | - | A | |
| | | $T_J = 125\text{ }^\circ\text{C}$ | - | 7.0 | - | | |
| Reverse recovery charge | Q_{rr} | $T_J = 25\text{ }^\circ\text{C}$ | - | 60 | - | nC | |
| | | $T_J = 125\text{ }^\circ\text{C}$ | - | 240 | - | | |
| Reverse recovery time | t_{rr} | $T_J = 125\text{ }^\circ\text{C}$ | $I_F = 15\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 390\text{ V}$ | - | 42 | - | ns |
| Peak recovery current | I_{RRM} | | | - | 21 | - | A |
| Reverse recovery charge | Q_{rr} | | | - | 480 | - | nC |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|--|----------------|--|------------|------|------------|---------------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T_J, T_{Stg} | | -65 | - | 175 | $^\circ\text{C}$ |
| Thermal resistance, junction to case | R_{thJC} | | - | 1.3 | 1.51 | $^\circ\text{C}/\text{W}$ |
| Thermal resistance, junction to ambient | R_{thJA} | Typical socket mount | - | - | 70 | |
| Thermal resistance, case to heatsink | R_{thCS} | Mounting surface, flat, smooth and greased | - | 0.5 | - | |
| Weight | | | - | 2.0 | - | g |
| | | | - | 0.07 | - | oz. |
| Mounting torque | | | 6 (5) | - | 12 (10) | kgf · cm (lbf · in) |
| Marking device | | Case style D ² PAK (TO-263AB) | ETH1506SH | | | |
| | | Case style TO-262AA | ETH1506-1H | | | |

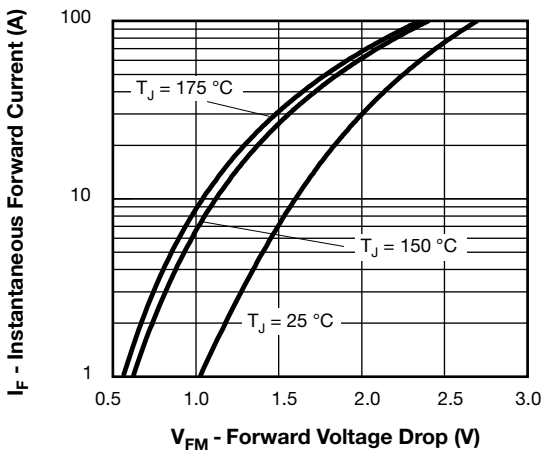


Fig. 1 - Typical Forward Voltage Drop Characteristics

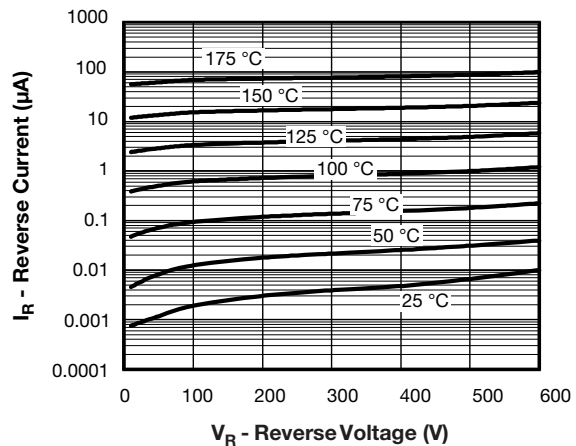


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

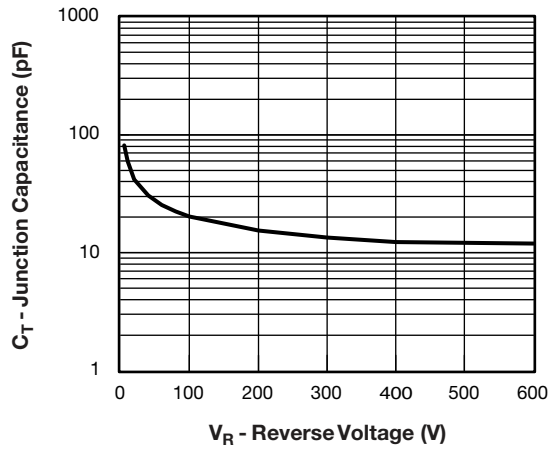


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

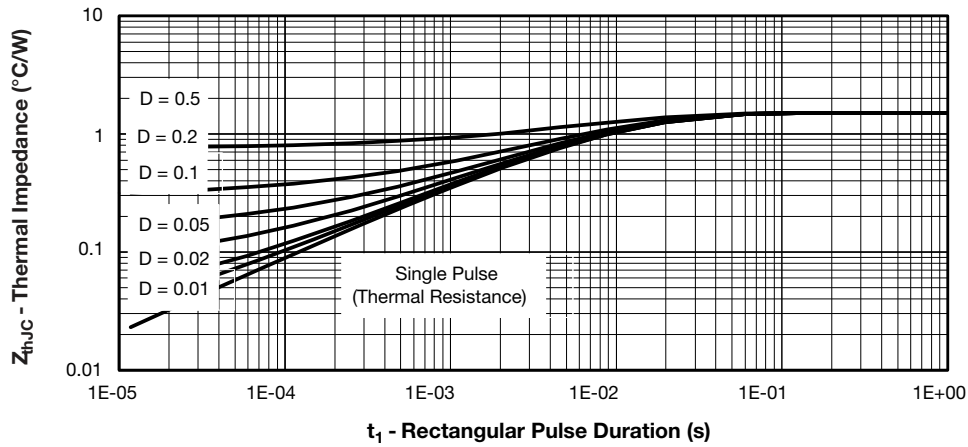


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

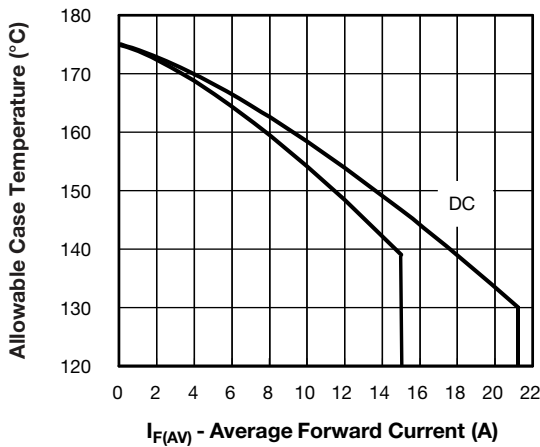


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

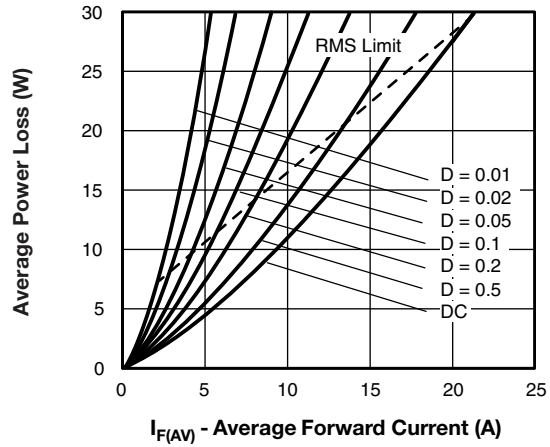


Fig. 6 - Forward Power Loss Characteristics

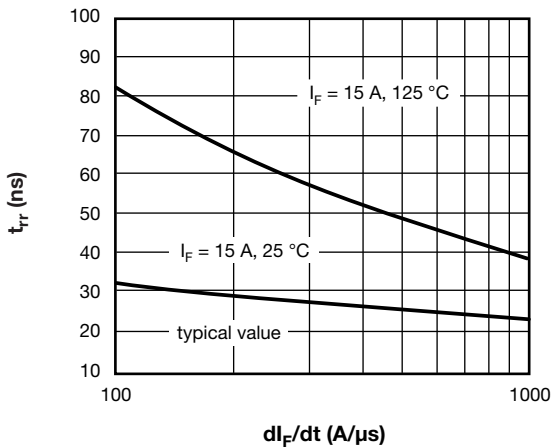


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

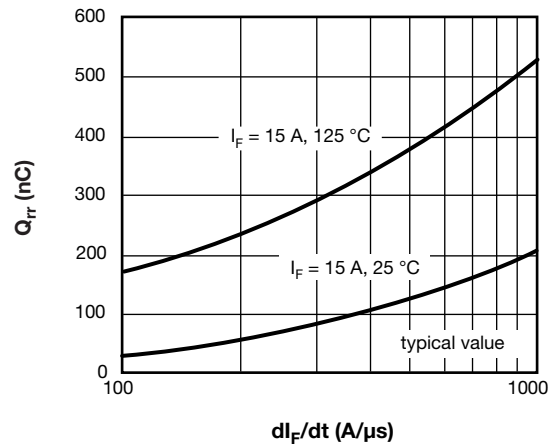


Fig. 8 - Typical Stored Charge vs. di_F/dt

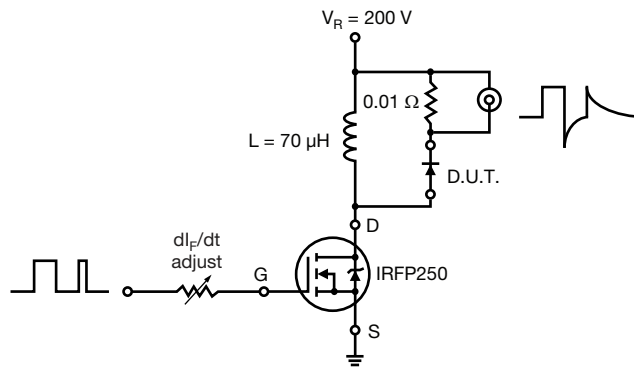
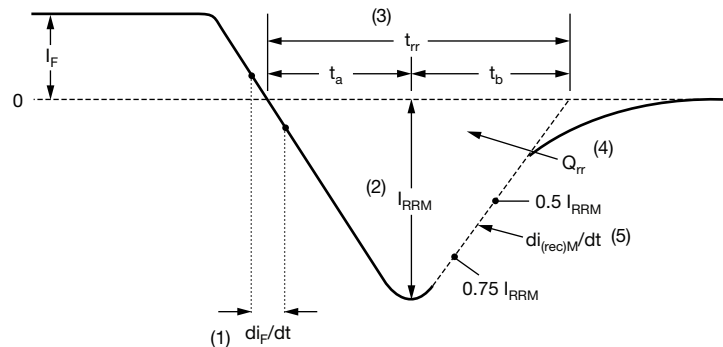


Fig. 9 - Reverse Recovery Parameter Test Circuit



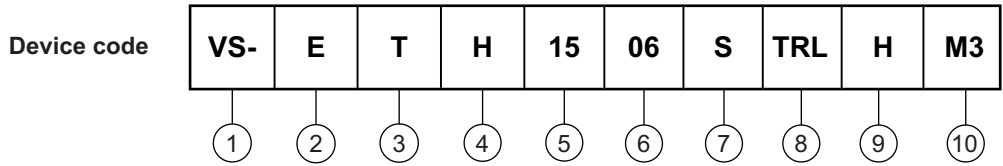
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Circuit configuration
E = single diode
- 3** - T = TO-220
- 4** - H = Hyperfast recovery time
- 5** - Current code (15 = 15 A)
- 6** - Voltage code (06 = 600 V)
- 7** - • S = D²PAK
• -1 = TO-262
- 8** - • None = tube
• TRL = tape and reel (left oriented, for D²PAK package)
• TRR = tape and reel (right oriented, for D²PAK package)
- 9** - H = AEC-Q101 qualified
- 10** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

| ORDERING INFORMATION (Example) | | |
|--------------------------------|---------------|-------------------------|
| PREFERRED P/N | BASE QUANTITY | PACKAGING DESCRIPTION |
| VS-ETH1506SHM3 | 50 | Antistatic plastic tube |
| VS-ETH1506-1HM3 | 50 | Antistatic plastic tube |
| VS-ETH1506STRRHM3 | 800 | 13" diameter reel |
| VS-ETH1506STRLHM3 | 800 | 13" diameter reel |

| LINKS TO RELATED DOCUMENTS | | |
|----------------------------|-------------------------------|--|
| Dimensions | D ² PAK (TO-263AB) | www.vishay.com/doc?95046 |
| | TO-262AA | www.vishay.com/doc?95419 |
| Part marking information | D ² PAK (TO-263AB) | www.vishay.com/doc?95444 |
| | TO-262AA | www.vishay.com/doc?95443 |
| Packaging information | D ² PAK (TO-263AB) | www.vishay.com/doc?95032 |

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



| SYMBOL | MILLIMETERS | | INCHES | | NOTES | SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|--------|-------|-------|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | | | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | | D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | | E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | e | 2.54 BSC | | 0.100 BSC | | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | H | 14.61 | 15.88 | 0.575 | 0.625 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | L | 1.78 | 2.79 | 0.070 | 0.110 | |
| c | 0.38 | 0.74 | 0.015 | 0.029 | | L1 | - | 1.65 | - | 0.066 | 3 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | L3 | 0.25 BSC | | 0.010 BSC | | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB

TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262



$\oplus 0.010 \text{ M} \text{ A} \text{ M} \text{ B}$



Lead assignments

- Diodes**
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



| SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | |
| A1 | 2.03 | 3.02 | 0.080 | 0.119 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 |
| c | 0.38 | 0.74 | 0.015 | 0.029 | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| e | 2.54 BSC | | 0.100 BSC | | |
| L | 13.46 | 14.10 | 0.530 | 0.555 | |
| L1 | - | 1.65 | - | 0.065 | 3 |
| L2 | 3.36 | 3.71 | 0.132 | 0.146 | |

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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